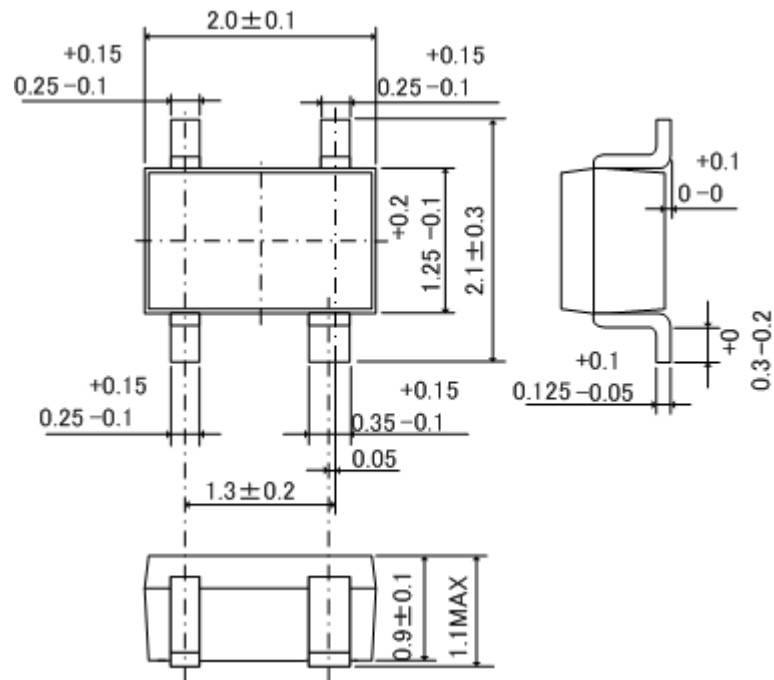


Packaging Information / Reference Pattern Layout Dimensions

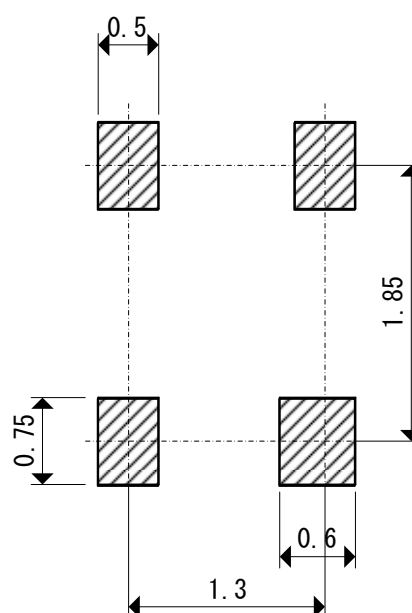
● SSOT-24

Unit: mm

■ Packaging Information



■ Reference Pattern Layout Dimension

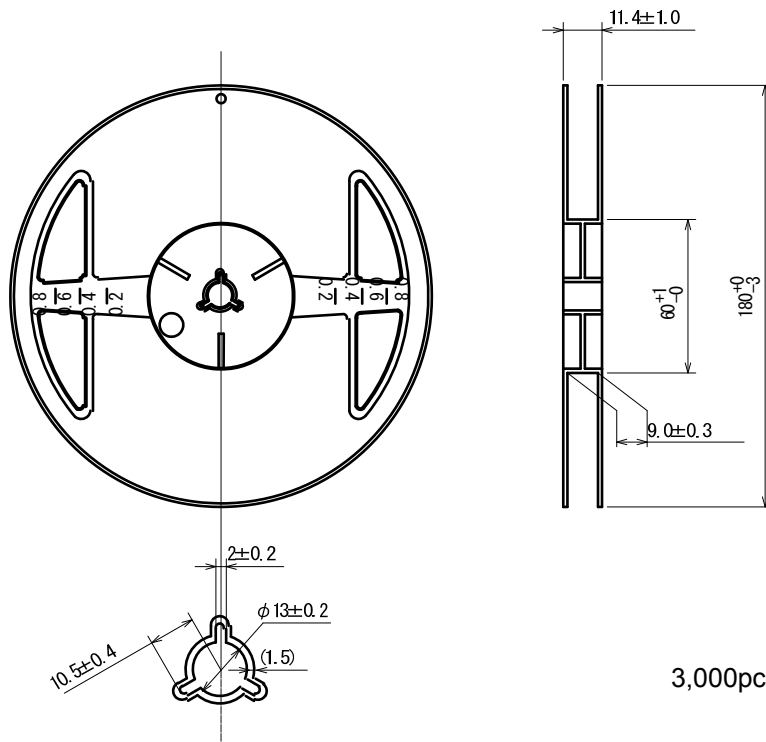


テーピング仕様 / Taping Specifications

SSOT-24

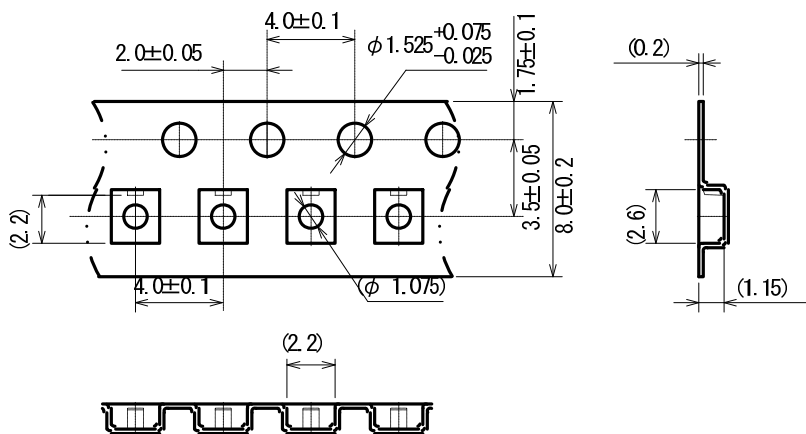
Unit: mm

●リール/Reel

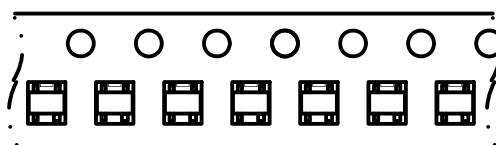


3,000pcs/reel

●テーピング仕様/Taping Specifications



direction of feed



R Type :[Device orientation : Right]

Standard feed

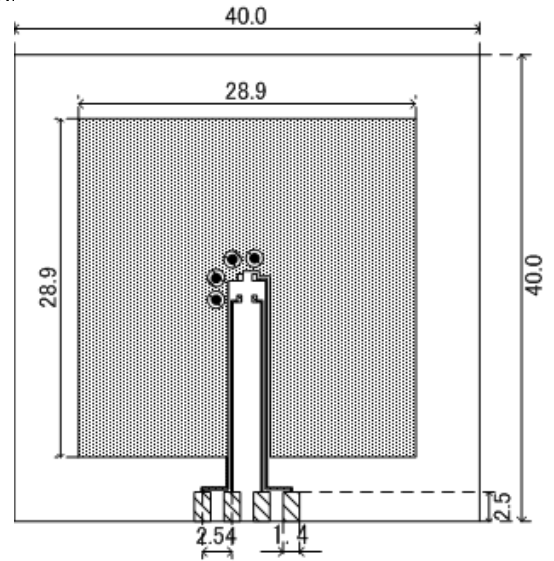
●SSOT-24 Power Dissipation

Power dissipation data for the SSOT-24 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as the reference data taken in the following condition.

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
Copper (Cu) traces occupy 50% of the board area
In top and back faces
Package heat-sink is tied to the copper traces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

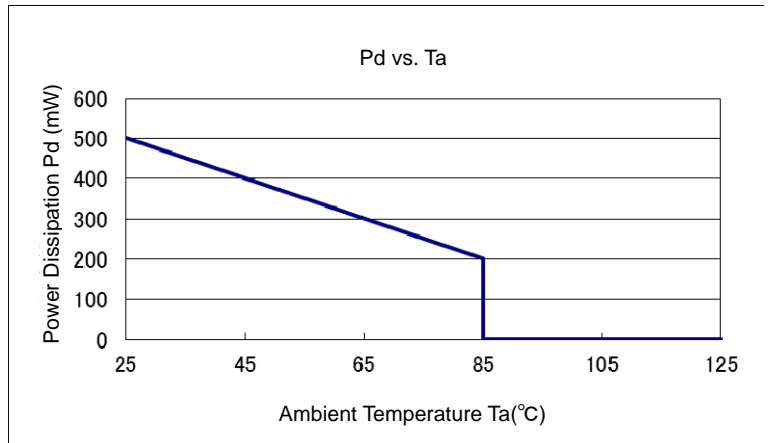


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature (85°C)

Board Mount (T_{jmax}=125°C)

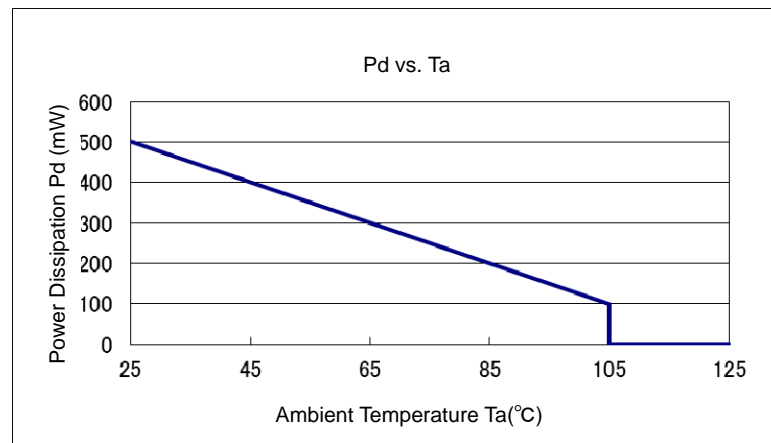
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	200	



3. Power Dissipation vs. Ambient Temperature (105°C)

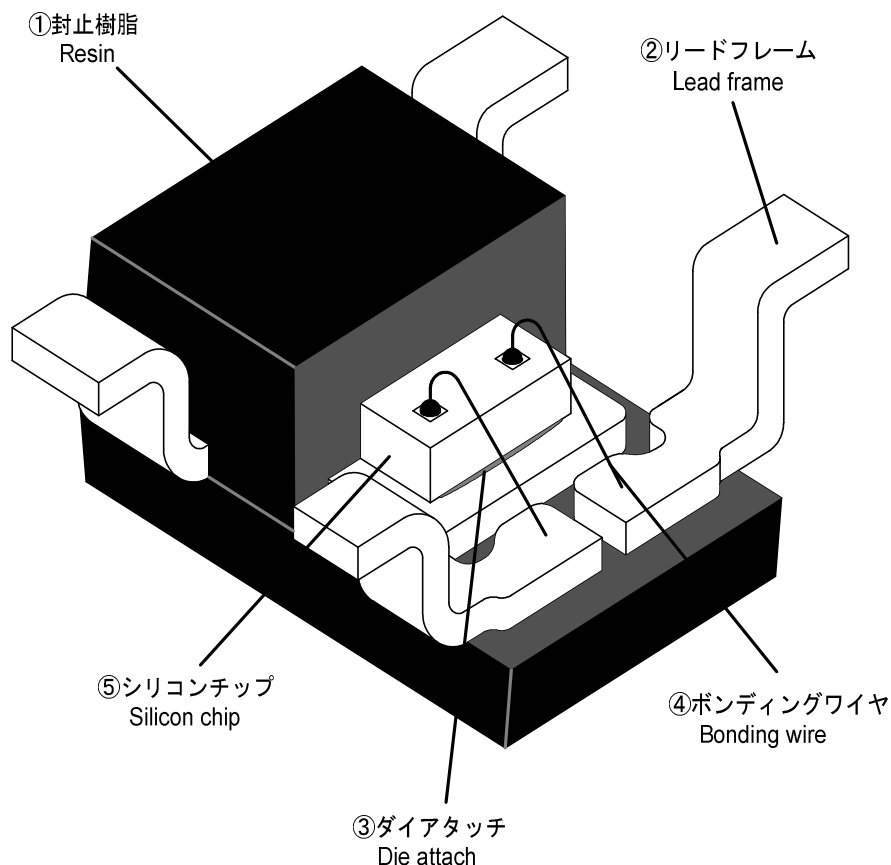
Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	100	



SSOT-24 構造図 SSOT-24 Perspective

RoHS対応品
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードフレーム Lead frame	銅系 Copper alloy	
端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
-----------------	-----------------------